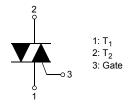


### FKPF5N80

### **Application Explanation**

- Switching mode power supply, light dimmer, electric flasher unit
- TV sets, stereo, refrigerator, washing machine, bread maker
- Electric blanket, solenoid driver, small motor control
- · Photo copier, electric tool





## **Bi-Directional Triode Thyristor Planar Silicon**

### Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DRM</sub>	Repetitive Peak Off-State Voltage (Note1)	800	V

Symbol	Parameter	Conditions		Rating	Units
I <sub>T (RMS)</sub>	RMS On-State Current	Commercial frequency, sine full wave 360° conduction, T <sub>C</sub> =104°C		5	Α
I <sub>TSM</sub>	Surge On-State Current	Sinewave 1 full cycle, peak value,	50Hz	50	Α
		non-repetitive		55	Α
I <sup>2</sup> t	I <sup>2</sup> t for Fusing	Value corresponding to 1 cycle of halfwave, surge on-state current, tp=10ms		12.5	A <sup>2</sup> s
di/dt	Critical Rate of Rise of On-State Current	I <sub>G</sub> = 2x I <sub>GT</sub> , tr ≤ 100ns		50	A/μs
$P_{GM}$	Peak Gate Power Dissipation			5	W
P <sub>G (AV)</sub>	Average Gate Power Dissipation			0.5	W
$V_{GM}$	Peak Gate Voltage			10	V
I <sub>GM</sub>	Peak Gate Current			2	Α
T <sub>J</sub>	Junction Temperature			- 40 ~ 125	°C
T <sub>STG</sub>	Storage Temperature			- 40 ~ 125	°C
V <sub>iso</sub>	Isolation Voltage	Ta=25°C, AC 1 minute, T <sub>1</sub> T <sub>2</sub> G terminal to case		1500	V

### **Thermal Characteristic**

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
$R_{th(J-C)}$	Thermal Resistance	Junction to case (Note 4)	ı	ı	3.9	°C/W

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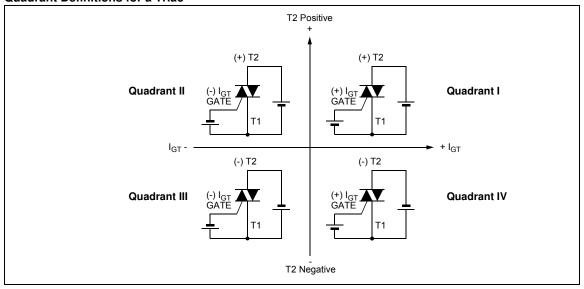
## $\textbf{Electrical Characteristics} \ \, \textbf{T}_{\text{C}} = 25^{\circ} \text{C unless otherwise noted}$

Symbol	Parameter		Test Condition		Min.	Тур.	Max.	Units
I <sub>DRM</sub>	Repetieive Peak Off-State Current		V <sub>DRM</sub> applied		-	-	20	μΑ
V <sub>TM</sub>	On-State Voltage		T <sub>C</sub> =25°C, I <sub>TM</sub> =7.5A Instantaneous measurement		-	-	1.5	V
	41.1.0	ı		T2(+), Gate (+)	-	-	1.5	V
$V_{GT}$	Gate Trigger Voltage (Note 2)	II	$V_D$ =12V, $R_L$ =20 $\Omega$	T2(+), Gate (-)	-	-	1.5	V
		III		T2(-), Gate (-)	-	-	1.5	V
	Gate Trigger Current (Note 2)	I	V <sub>D</sub> =12V, R <sub>L</sub> =20Ω	T2(+), Gate (+)	-	-	20	mA
$I_{GT}$		II		T2(+), Gate (-)	-	-	20	mA
		III		T2(-), Gate (-)	-	-	20	mA
V <sub>GD</sub>	Gate Non-Trigger Voltage		T <sub>J</sub> =125°C, V <sub>D</sub> =1/2V <sub>DRM</sub>		0.2	-	-	V
I <sub>H</sub>	Holding Current		V <sub>D</sub> = 12V, I <sub>TM</sub> = 1A		-	-	30	mA
IL	Latching Current	I, III	V <sub>D</sub> = 12V, I <sub>G</sub> = 1.2I <sub>GT</sub>		-	-	30	mA
		II			-	-	50	mA
dv/dt	Critical Rate of Rise of Off-State Voltag		$V_{DRM}$ = Rated, $T_j$ = 125°C, Exponential Rise		-	300	-	V/μs
(dv/dt) <sub>C</sub>	Critical-Rate of Rise of Off-State Commutating Voltage (Note 3)				10	-	-	V/μs

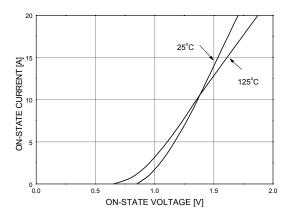
- Notes:
  1. Gate Open
  2. Measurement using the gate trigger characteristics measurement circuit
  3. The critical-rate of rise of the off-state commutating voltage is shown in the table below
  4. The contact thermal resistance R<sub>TH(c-f)</sub> in case of greasing is 0.5 °C/W

V <sub>DRM</sub> (V)	Test Condition	Commutating voltage and current waveforms (inductive load)
FKPF5N80	1. Junction Temperature  T <sub>J</sub> =125°C  2. Rate of decay of on-state commutating current (di/dt) <sub>C</sub> = - 3.0A/ms  3. Peak off-state voltage  V <sub>D</sub> = 400V	Supply Voltage  Time  Main Current  Main Voltage  (dv/dt) <sub>C</sub> Time  V <sub>D</sub>

### **Quadrant Definitions for a Triac**



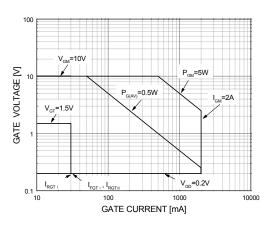
# **Typical Curves**



NUMBER OF CYCLES AT 50Hz AND 60Hz

Figure 1. Maximum On-state Characteristics

Figure 2. Rated Surge On-state Current



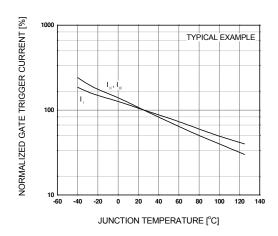
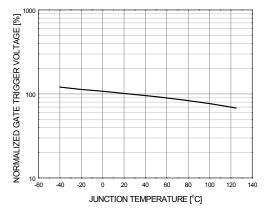


Figure 3. Gate Characteristics

Figure 4. Gate Trigger Current vs Tj



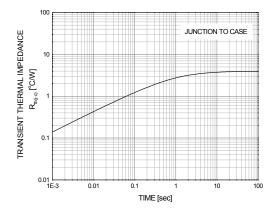


Figure 5. Gate Trigger Voltage vs Tj

Figure 6. Transient Thermal Impedance

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# Typical Curves (Continues)

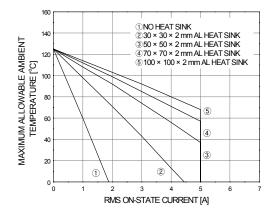


Figure 7. Allowable Ambient Temperature vs Rms On-state Current

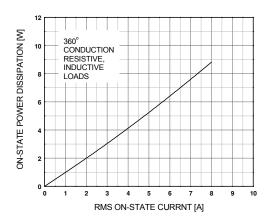


Figure 9. Maximum On-state Power Dissipation

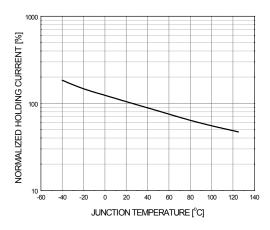


Figure 11. Holding Current vs
Junction Temperature

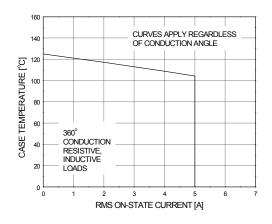


Figure 8. Allowable Case Temperature vs Rms On-state Current

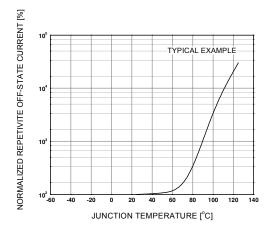


Figure 10. Repetitive Peak Off-state Current vs Junction Temperature

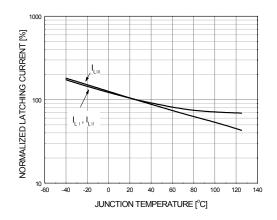


Figure 12. Laching Current vs
Junction Temperature

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# Typical Curves (Continues)

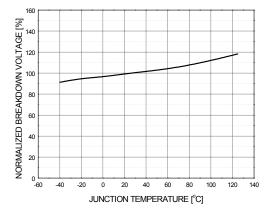


Figure 13. Breakover Voltage vs. Junction Temperature

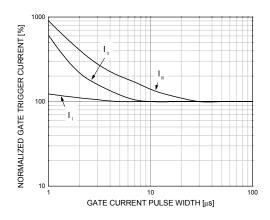


Figure 14. Gate Trigger Current vs.

Gate Current Pulse Width

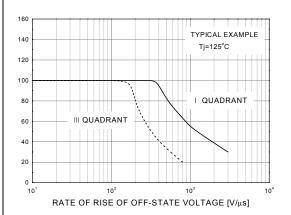


Figure 15. Breakover Voltage vs. Rate of Rise of Off-State Voltage

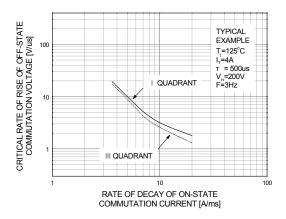
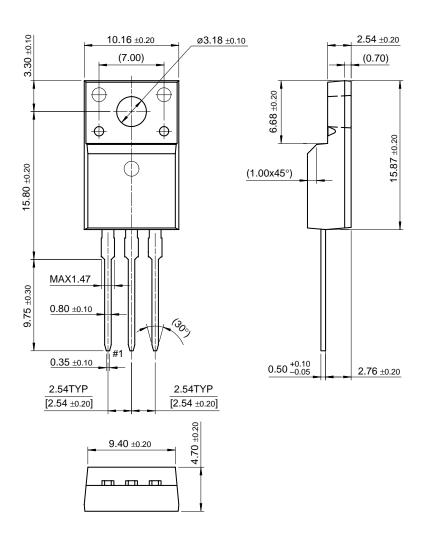


Figure 16. Commutation Characteristics

# **Package Dimension**

# TO-220F



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